



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## In re Application of:

Teck Kheng Lee

**Serial No.:** 10/829,603

Filed: April 22, 2004

For: METHODS FOR ASSEMBLY AND

PACKAGING OF FLIP CHIP

CONFIGURED DICE WITH INTERPOSER

Confirmation No.: 6862

Examiner: S. Geyer

Group Art Unit: 2812

Attorney Docket No.: 2269-4974.2US

(00-0693.02/US)

Notice of Allowance Mailed:

February 7, 2006

## NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV 827473108 US

Date of Deposit with USPS: May 4, 2006

Person making Deposit: Timothy Palfreyman

## AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 19 of this paper;

Amendments to the claims are set forth in the listing of the claims that begins on page 20 of this paper;

Corrections to the drawings are summarized on page 25 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 26 of this paper.